56th IEEE International Symposium on Multiple-Valued Logic

ISMVL 2026

May 19 – 21, 2026, Sendai, Miyagi, Japan

Call for Papers

"Zuiganji"   "Statue of Masamune Date"   "Matsushima"

The IEEE Computer Society's Technical Community on Multiple-Valued Logic will hold its 56th annual symposium in Sendai, Miyagi, Japan, in May 2026. You are invited to submit an original paper, survey, or tutorial paper on any subject in the area of multiple-valued logic, including but not limited to:

Algebra and Formal Aspects	*Logic Design and Switching Theory*
Automatic Reasoning	*Test and Verification*
Logic Programming	*Spectral Techniques*
Philosophical Aspects of MVL	*Circuit/Device Implementation*
Fuzzy Logic and Soft Computing	*VLSI Architecture and Computing*
Data Mining	*System-on-Chip Technology*
Machine Learning and Robotics	*MVL Aspects of Nanotechnology*
Quantum Computing	*MVL Aspects of Medical Technologies*
Reversible Computing	*MVL Approaches to Big Data*

Authors should submit papers in PDF format on the conference website by **November 1, 2025**. Each manuscript should include a 50-to-100-word abstract and should not exceed 6 pages in the 2-column IEEE Proceedings format. Special issues of some journals are planned for selected ISMVL 2026 papers.

Authors will be notified about acceptance by **February 1, 2026**. Camera-ready copies of accepted papers are due on **March 1, 2026**. For submission details, please visit the symposium website: **https://mvl.jpn.org/ISMVL2026/**

> **Travel Support for Students:**
> We plan to secure some money to support students in attending ISMVL 2026. If the first author of the paper is a student and the student is going to present the paper at ISMVL, then he/she is eligible to receive a travel grant. When submitting a paper, please indicate whether the first author is a student.

The 35th International Workshop-Symposium on Post-Binary ULSI Systems will be held on May 18th at the same venue as ISMVL 2026. Information on accommodations and transportation to the symposium venue in Sendai will be provided at a later date. For additional information, please contact:

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